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Part Number: [0739426200](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 72 Circuits

Documents:
[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Drawing \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73942](#)
Application Backplane
Comments Solder Tail
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.138 In
PC Tail Length (mm) 3.50 mm
PCB Retention None
PCB Thickness Recommended (in) 0.098 In
PCB Thickness Recommended (mm) 2.50 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.5
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C

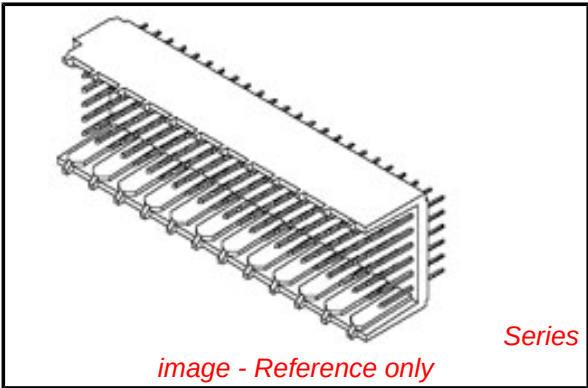


image - Reference only

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[73942Series](#)

Mates With
[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.
Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

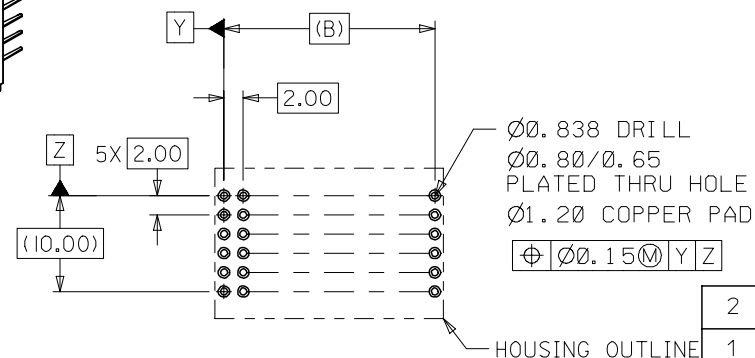
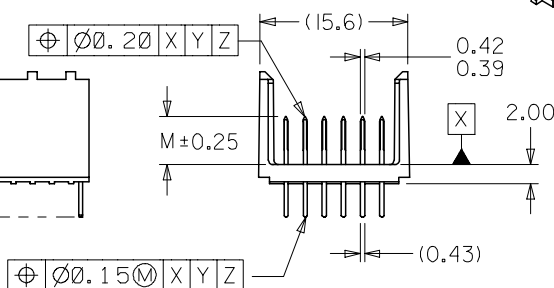
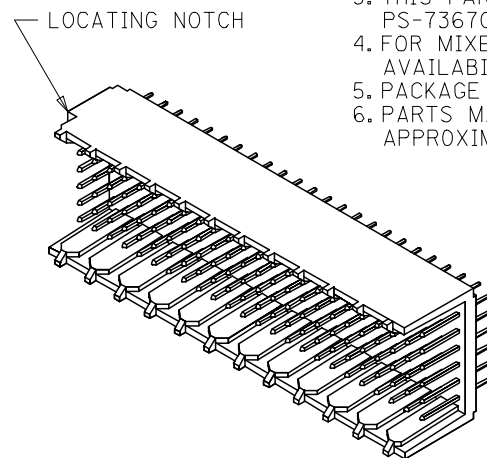
Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73942-001

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1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED,
UL94V-O, COLOR: BLACK,
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA;
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA;
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION
PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR
AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE,
APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

	2	A
E	1	G
	SHT	REV

- SEE NOTE 6

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRAWN BY: IBARRA 2007/03/13 CHK'D BY: BARKER 2007/03/21 APPR: MILLER 2007/03/22	QUALITY SYMBOLS ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY JB INGHAM	DATE 1998/01/13	TITLE SALES ASSY HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION			
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	CHECKED BY SREED	DATE 1998/01/13				
			2 PLACES ± 0.05 ± ---	1 PLACE ± 0.10 ± ---	APPROVED BY CB IXLER	DATE 1998/01/13				
			ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.		SHEET NO. 1 OF 2	
G	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE CHART		SD-73942-001					
			SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

MATERIAL NUMBER ASSIGNMENT

73942-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	23.84	22.00	2.0
1	144	47.84	46.00	2.0
2	72	23.84	22.00	2.5
3	144	47.84	46.00	2.5
4	72	23.84	22.00	3.0
5	144	47.84	46.00	3.0
6	72	23.84	22.00	3.5
7	144	47.84	46.00	3.5

NUMBER	DIM "M"
0	5.0
1	5.5
2	6.0

SEE SHEET 1 EC No. U81577 DRWN:JBINGHAM 98/0203 CHK: SREED 98/0203 APPR:CBIXLER 98/0203 A	DESCRIPTION REV	QUALITY SYMBOLS MAJOR CRITICAL	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE --:--	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT	REV
					DRAWN BY & DATE JBINGHAM 98/01/13			TITLE: SALES ASSY, HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION		MATERIAL NO. DRAWING NO. SHEET NO.	2
					CHECKED BY & DATE SREED 98/01/13			MOLEX INCORPORATED			
					APPROVED BY & DATE CBIXLER 98/01/13			SEE CHART SD-73942-001			
					1 PLACE ±0. N/A ±.			CAD FILENAME S73942X2.DGN			
				4 PLACES ±0. ±.							
				3 PLACES ±0. ±.							
				2 PLACES ±0. N/A ±.							
				1 PLACE ±0. N/A ±.							
				ANGULAR: ± °							
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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